

SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG128128S04A-N-B0

Doc. Version: U2						
Customer Appr	oval:					
☐ Accept			☐ Reject			
YEEBO	NAME	SIGNATURE	DATE			
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APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

Sample Version	DOC. Version	DATE		CHANGED BY	
В0	00	2017-03-01	SPEC ONLY	First issue	Angus/Fen
В0	01	2017-05-31	FULL SPEC	First SAMPLE	Angus/Fen
В0	02	2018-04-24	FULL SPEC	Modify LCM Drawing P5 Absolute Maximum Ratings P6	Gavin/Fen



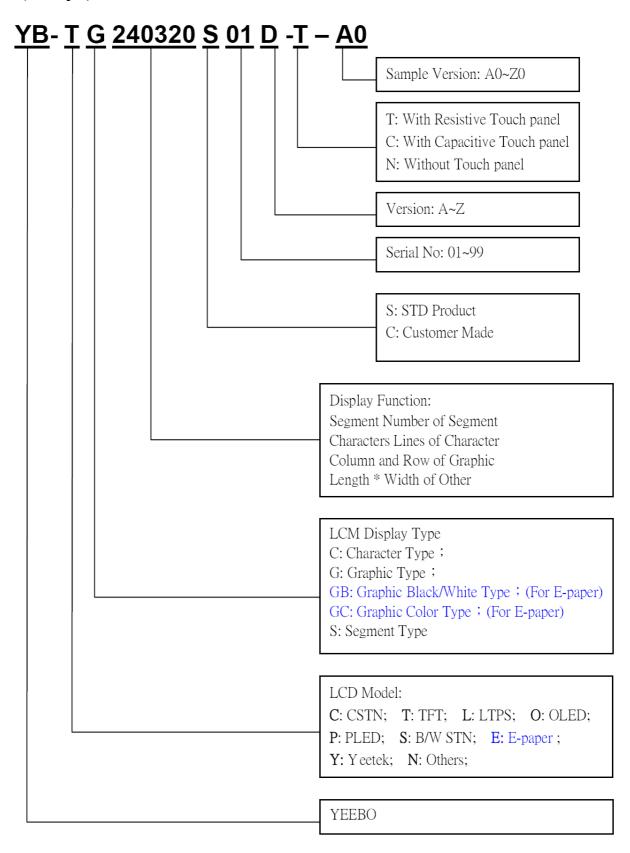
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3.Module Numbering System:

(Example)



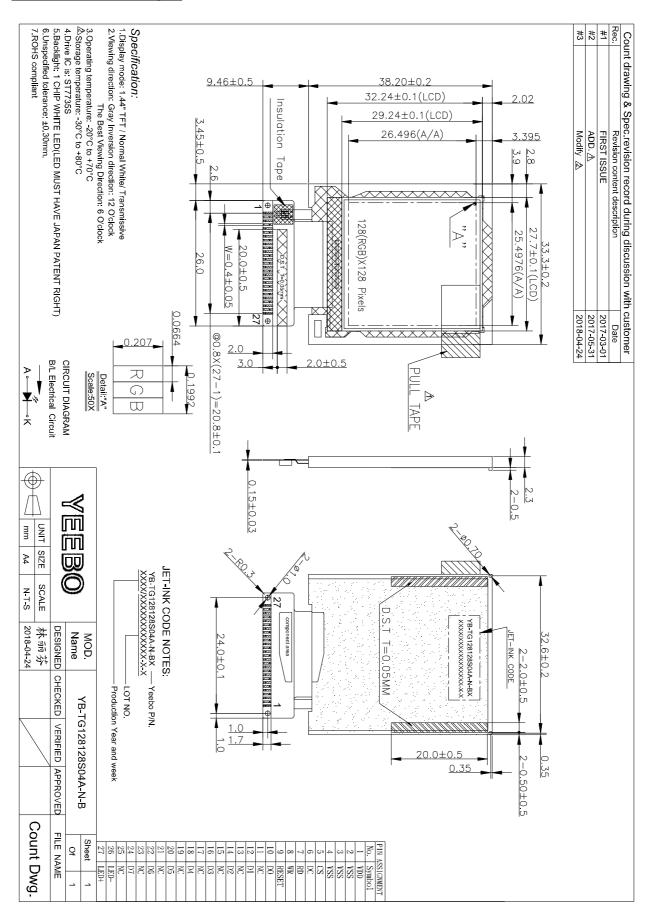


4. General Specification:

ITEM	CONTENTS			
Module Size	33.3 (W) *38.2(H) * 2.3(T) mm			
Module Size(With FPC)	33.3 (W) * 47.66(H) * 2.3(T) mm			
Display Size(Diagonal)	1.44 inch			
Display Format	128(RGB)* 128 Pixels			
Active Area	25.4976(W) * 26.496 (H) mm			
Pixel Pitch	0.1992* 0.207 mm			
LCD Type	TFT (262K)/ Transmissive / NW			
View Angle(Gray Inversion)	12 O'clock			
The Best Viewing Direction:	6 O'clock			
Controller IC	ST7735S			
Weight	4.2g			



5. LCM drawing:





6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Input Voltage	$V_{ m DD}$	-0.3	-	+4.6	Volt	Note1
Supply Voltage	$V_{ m DDI}$	-0.3	-	+4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70	$^{\circ}\!\mathbb{C}$	-
Storage Temperature	Tstg	-30	-	+80	$^{\circ}\!\mathbb{C}$	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions

(Ta=25°C)

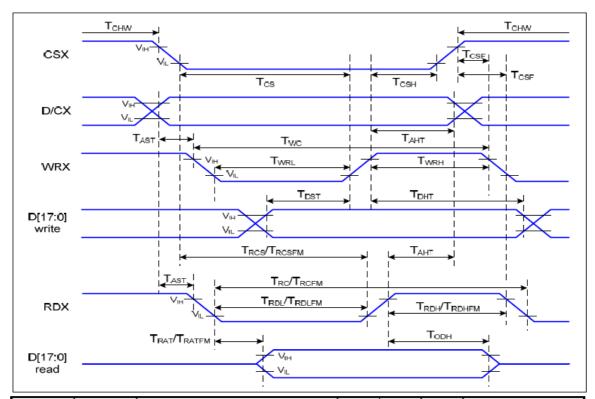
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply voltage	VDD	-	2.5	2.8	3.3	Volt
Interface Operation Voltage	VDDI	-	1.65	1.8	3.3	Volt
Input Voltage	V _{IH}	-	0.7 * V _{DDI}	-	$V_{ m DDI}$	V
input voltage	V _{IL}	-	VSS	-	0.3 * V _{DDI}	V
Output Voltage	V_{OH}	-	0.8 * V _{DDI}		VDDI	
Sulput Vollage	V _{OL}	-	VSS		0.2 * V _{DDI}	
Power Supply Current for LCM	I_{DD}	VDD=2.8V	-	2.2	3.3	mA

Note: VSS=0V



6-3 Timing Characteristics

Parallel Interface Characteristics: 18, 16, 9 or 8-bit Bus (8080 Series MCU Interface)



Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	TAST	Address Setup Ttime	0		ns	
DICX	TAHT	Address Hold Time (Write/Read)	10		ns	-
	TCHW	Chip Select "H" Pulse Width	0		ns	
	TCS	Chip Select Setup Time (Write)	15		ns	
007	TRCS	Chip Select Setup Time (Read ID)	45		ns	
CSX	TRCSFM	Chip Select Setup time (Read FM)	355		ns	-
	TCSF	Chip Select Wait Time (Write/Read)	10		ns	
	TCSH	Chip Select Hold Time	10		ns	
	TWC	Write Cycle	66		ns	
WRX	TWRH	Control Pulse "H" Duration	15		ns	
	TWRL	Control Pulse "L" Duration	15		ns	
	TRC	Read Cycle (ID)	160		ns	
RDX (ID)	TRDH	Control Pulse "H" Duration (ID)	90		ns	When Read ID Data
	TRDL	Control Pulse "L" Duration (ID)	45		ns	
RDX	TRCFM	Read Cycle (FM)	450		ns	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
(FM)	TRDHFM	Control Pulse "H" Duration (FM)	90		ns	When Read from Frame Memory
(FIVI)	TRDLFM	Control Pulse "L" Duration (FM)	355		ns	Frame Wemory
	TDST	Data Setup Time	10		ns	
	TDHT	Data Hold Time	10		ns	
D[17:0]	TRAT	Read Access Time (ID)		40	ns	For CL=30pF
	TRATFM	Read Access Time (FM)		340	ns	
	TODH	Output Disable Time	20	80	ns	

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Figure 2 Rising And Falling Timing for Input And Output Signal

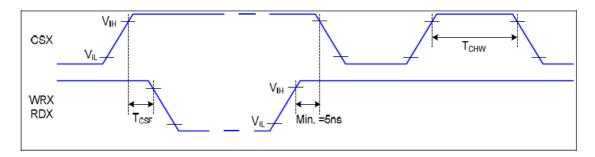


Figure 3 Chip Selection (CSX) Timing

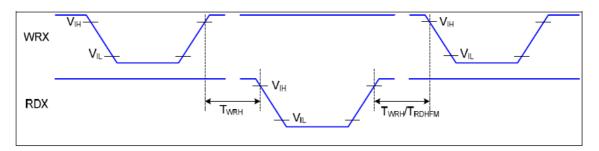


Figure 4 Write-to-Read And Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



7. Optical Characteristics:

140	m Cymh		Canditions	Specifications		ons	T1:4	Note
Iten	1	Symbol	Conditions	Min	Тур	Max	Unit	Note
Transmit (Withou		T(%)	_	-	16.5	-	-	-
Contrast	Ratio	CR	⊕=0 Normal Viewing angle	-	450	-		(1) (2)
Response	e time	TR+TF	_	-	16	-	ms	(1) (3)
	Hor.	Өх+		-	60	-		
Viewin	Viewin 1101.	Өх-	CR≧10	-	60	-	deg.	_
g angle	\/or	⊖y+	$O_N = 10$	-	60	-	ueg.	_
	Ver.			-	50	-		

Measuring Condition

1. Measuring surrounding: dark room 2. Ambient temperature: 25±2°C

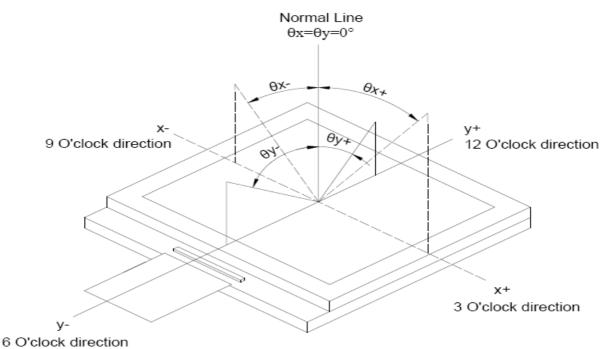
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	D 1	X		0.563	0.613	0.663
	Red	у		0.310	0.360	0.410
Chromaticity Coordinates (Transmissive)	Green	X	$\theta = \phi = 0^{\circ}$ LED Backlight	0.271	0.321	0.371
		у		0.511	0.561	0.611
	Blue	X		0.092	0.142	0.192
		у		0.050	0.10	0.150
	White	X		0.235	0.285	0.335
		y		0.253	0.303	0.353



Note (1) Definition of Viewing Angle:

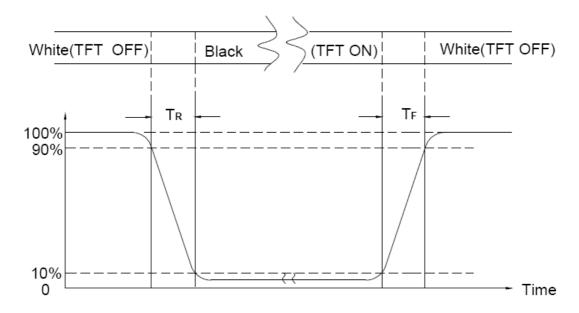


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black

Note (3) Definition of Response Time: Sum of TR and TF



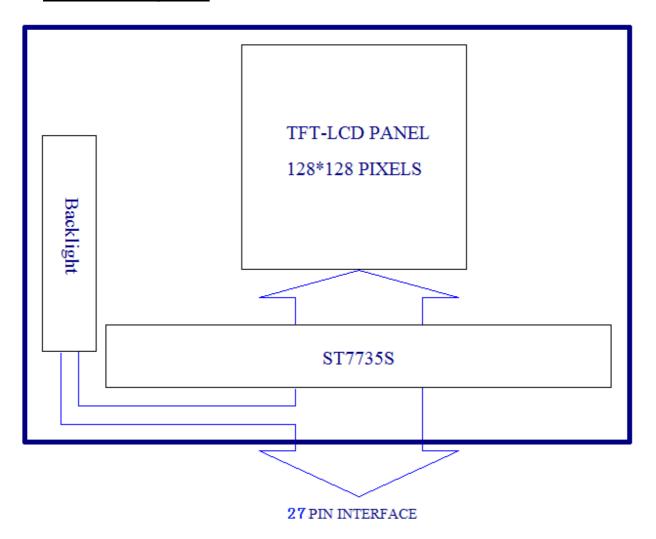


8. Interface Pin Assignment:

No.	Symbol	Function
1	VDD	System Power.
2~4	VSS	System Ground.
5	CS	Chip Selection Pin
6	DC	this pin is used as D/CX (data/ command selection).
7	RD	Read Enable in 8080 MCU Parallel Interface
8	WR	Write Enable in MCU Parallel Interface
9	RESET	System reset pin.
10	D0	Data bus.
11	NC	NC
12	D1	Data bus.
13	NC	NC
14	D2	Data bus.
15	NC	NC
16	D3	Data bus.
17	NC	NC
18	D4	Data bus.
19	NC	NC
20	D5	Data bus.
21	NC	NC
22	D6	Data bus.
23	NC	NC
24	D7	Data bus.
25	NC	NC
26	LED-	Cathode pin of backlight
27	LED+	Anode pin of backlight



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

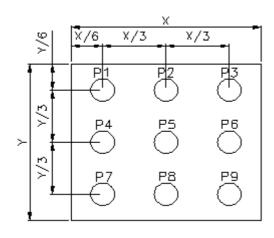
(Ta=25°C)

2: 2 www 1 10 0 ww 22 2 2 www.m.g.m.						,	
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	-	20	-	mA	V=3.2V	
Supply Voltage	V	2.7	3.0	3.3	V		
Luminous Intensity for LCM	IV	-	160	-	Cd/m ²	If=20mA	2
Uniformity for LCM	-	70	1	-	%		3
Life Time	-	20000	-	-	Hr.		4
Color				Wh	ite		

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area) Internal Circuit Diagram



BLG CIRCUIT DIAGRAM

(Effective spatial Distribution)

Using aperture of 1°, distance 50cm.



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 60° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -10°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 60°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -20°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 40°C,75%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: $-20^{\circ}\mathbb{C}$ for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +60°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: $10\text{Hz} \sim 55\text{Hz}$ Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: ± 4 KV 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}$ C), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to ISO2859-1. General Inspection Level $\, {\rm I\hspace{-.1em}I} \,$ take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65% Minor defect: AQL = 2.5% Total defects: AQL = 2.5%

12-3. Non- conforming Analysis & Deal With Manners

- a. Non-conforming Analysis:
- (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
- (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
- (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

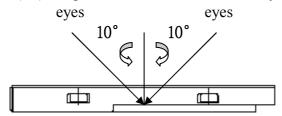
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

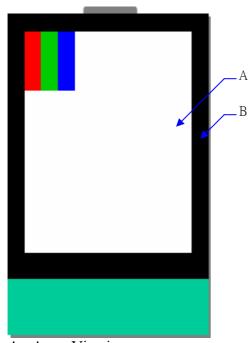


12-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
- (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at $30\pm5cm$.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)
- b. Basic principle:
 - (i) It will accord to the AQL when the standard can not be described.
 - (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - (iii) Must add new item on time when it is necessary.
 - c. Standard of inspection: (Unit: mm)



12-6. Inspection specification
Defect out of viewing area can be neglected.

NO	Item	Criterion A				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 2.3 Not visible through 5% ND filter 			2.5	
02	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As foll $\Phi = (X+Y)/2$ $X \qquad \qquad$	more	Size(mm) $Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ \le 0.30$ 0.30 < Φ than two	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm.	2.5
03		→ L ₩	Length(mm) L≦3.0 L≤2.5	ing) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5



NO	Item	Criterion			
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5		
05	Scratches	Follow NO.3 -2 Line Type.			
06	Mura	Not visible through 5% ND filter in 50% gray.	2.5		
07	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.1 General glass chip: 7.1.1 Chip on panel surface and crack between panels:	2.5		



NO	Item	Criterion			
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 8.1 Protrusion over terminal: 8.1.1 Chip on electrode pad:			
		$y{:} \ Chip \ width \qquad x{:} \ Chip \ length \qquad z{:} \ Chip \\ thickness \\ y \leq 0.5 mm \qquad x \leq 1/8a \qquad 0 < z \leq t \\ 8.1.2 \\ Non-conductive \ portion:$			
08	Glass crack	y z z z z z z z z z z z z z z z z z z z	2.5		
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$			
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 8.1.3 Substrate protuberance and internal crack 			
		y: width x: length			
		$y \le 1/3L$ $X \le a$			



NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	 10.1 Illumination source flickers when lit. 10.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 10.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	 12.1 COB seal may not have pinholes larger than 0.2mm or contamination. 12.2 COB seal surface may not have pinholes through to the IC. 12.3 The height of the COB should not exceed the height indicated in the assembly diagram. 12.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 12.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 12.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
13	FPC	13.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 13.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
14	Soldering	14.1 No cold solder joints, missing solder connections, oxidation or icicle.14.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion				
		Symbols: x: Chip length k: Seal width length L: Electrode pad length 15.1 General glass cl 15.1.1 Chip on panel	y: Chip width z: t: Touch Panel Total t		side	AQL
		z: Chip thickness	y: Chip width	x: Chip length		
15	Touch Panel Chipped glass	Z≦t	$\leq 1/2$ k and not over viewing area	x ≤ 1/8a		2.5
		 ⊙ Unit: mm ⊙ If there are 2 or m 15.1.2 Corner crack: 	nore chips, x is the total	length of each chip		2.5
		z: Chip thickness	y: Chip width	x: Chip length		
		z≦t	≤ 1/2 k and not over viewing area	x≤1/8a		
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip		



NO	Item	Criterion	AQL
16	Touch Panel(Fish eye、dent and bubble on film)		2.5
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5
18	Touch Panel Linearity	Less than 2.5% is acceptable.	
19	LCD Ripple	Touch the touch panel, cannot see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5
20	General appearance	 20.1 Pin type must match type in specification sheet. 20.2 LCD pin loose or missing pins. 20.3 Product packaging must the same as specified on packaging specification sheet. 20.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment. YEEBO ROHS requirement is based on European Union Directive 2011/65/EU(ROHS) Requirements and Update.

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